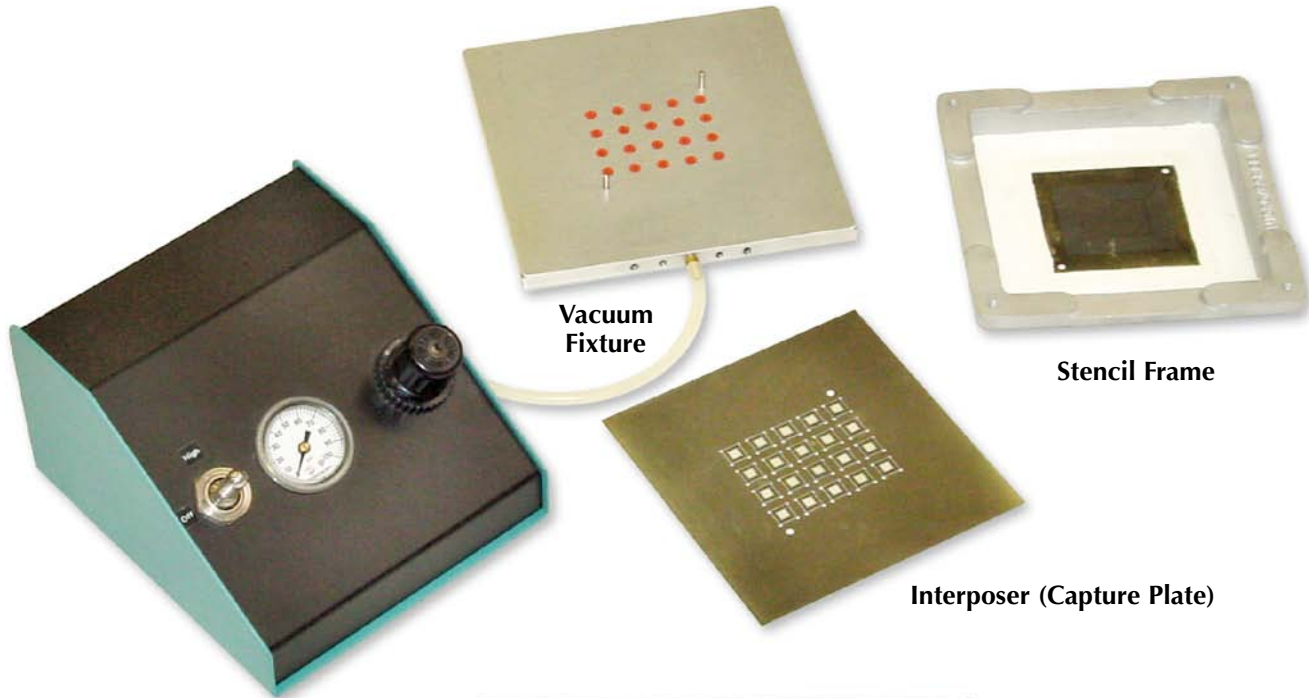


# QFN/MLF<sup>®</sup> Reballing (Pasting) Kit

The Interposer is placed onto the Vacuum Fixture using the tooling pins. Twenty QFN/MLF devices are loaded into the Interposer (Capture Plate). The Stencil Frame is then mounted onto the QFN Devices and solder paste is applied. The Vacuum Module is activated and the Stencil Frame is removed. Parts can be reflowed using a hot plate or hot gas tool. Please e-mail or fax a specification sheet of your QFN/MLF device to Air-Vac.



Vacuum Module

Vacuum Fixture

Stencil Frame

Interposer (Capture Plate)

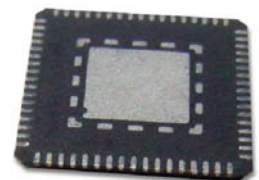
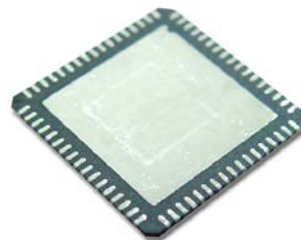


Release Plate

\*Patent Pending



Cleaning Station



QFN/MLF Devices  
(Quad Flat no leads/MicroLeadFrame<sup>®</sup>)